

GENERAL DESCRIPTION

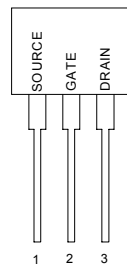
This N-Channel enhancement mode field effect transistor is produced using high cell density, DMOS technology. These products have been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance. It can be used in most applications requiring up to 200mA DC and can deliver pulsed currents up to 500mA. This product is particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

FEATURES

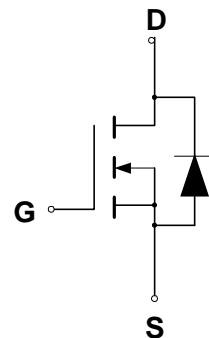
- ◆ High Density Cell Design for Low $R_{DS(ON)}$
- ◆ Voltage Controlled Small Signal Switch
- ◆ Rugged and Reliable
- ◆ High Saturation Current Capability

PIN CONFIGURATION

TO-92
Top View



SYMBOL



N-Channel MOSFET

ORDERING INFORMATION

| Part Number | Package |
|-------------|---------|
| CMT2N7000 | TO-92 |

ABSOLUTE MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|--|----------------|------------|-------|
| Drain Source Voltage | V_{DSS} | 60 | V |
| Drain-Gate Voltage ($R_{GS} = 1.0M\Omega$) | V_{DGR} | 60 | V |
| Drain to Current — Continuous | I_D | 200 | mA |
| — Pulsed | I_{DM} | 500 | |
| Gate-to-Source Voltage — Continue | V_{GS} | ± 20 | V |
| — Non-repetitive | V_{GSM} | ± 40 | V |
| Total Power Dissipation | P_D | 350 | mW |
| Derate above 25°C | | 2.8 | mW/°C |
| Operating and Storage Temperature Range | T_J, T_{STG} | -55 to 150 | °C |
| Thermal Resistance — Junction to Ambient | θ_{JA} | 357 | °C/W |
| Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds | T_L | 300 | °C |

ELECTRICAL CHARACTERISTICS

Unless otherwise specified, $T_J = 25^\circ\text{C}$.

| | | CMT2N7000 | | | |
|--|--|--------------|-----|------------|---------------------|
| Characteristic | Symbol | Min | Typ | Max | Units |
| Drain-Source Breakdown Voltage ($V_{GS} = 0\text{ V}$, $I_D = 10\text{ }\mu\text{A}$) | $V_{(BR)DSS}$ | 60 | | | V |
| Drain-Source Leakage Current ($V_{DS} = 48\text{ V}$, $V_{GS} = 0\text{ V}$) ($V_{DS} = 48\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 125^\circ\text{C}$) | I_{DSS} | | | 1.0 1.0 | μA mA |
| Gate-Source Leakage Current-Forward ($V_{gsf} = 15\text{ V}$, $V_{DS} = 0\text{ V}$) | I_{GSSF} | | | -10 | nA |
| Gate Threshold Voltage * ($V_{DS} = V_{GS}$, $I_D = 1.0\text{ mA}$) | $V_{GS(th)}$ | 0.8 | | 3.0 | V |
| Static Drain-Source On-Resistance * ($V_{GS} = 10\text{ V}$, $I_D = 0.5\text{ A}$) | $R_{DS(on)}$ | | | 5.0 | Ω |
| Drain-Source On-Voltage * ($V_{GS} = 10\text{ V}$, $I_D = 0.5\text{ A}$) | $V_{DS(on)}$ | | | 2.5 | V |
| On-State Drain Current * ($V_{GS} = 5\text{ V}$, $V_{DS} = 10\text{ V}$) | $I_{d(on)}$ | 60 | | | mA |
| Forward Transconductance ($V_{DS} = 10\text{ V}$, $I_D = 200\text{ mA}$) * | g_{FS} | 100 | | | mmhos |
| Input Capacitance | $(V_{DS} = 25\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1.0\text{ MHz}$) | C_{iss} | | 60 | pF |
| Output Capacitance | | C_{oss} | | 25 | pF |
| Reverse Transfer Capacitance | | C_{rss} | | 5.0 | pF |
| Turn-On Delay Time | $(V_{DD} = 15\text{ V}$, $I_D = 500\text{ mA}$, $V_{gen} = 10\text{ V}$, $R_G = 25\Omega$, $R_L = 30\Omega$) * | $t_{d(on)}$ | | 10 | ns |
| Turn-Off Delay Time | | $t_{d(off)}$ | | 10 | ns |

* Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$

TYPICAL ELECTRICAL CHARACTERISTICS

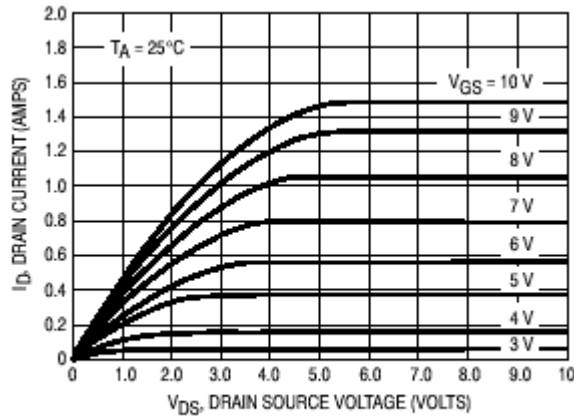


Figure 1. Ohmic Region

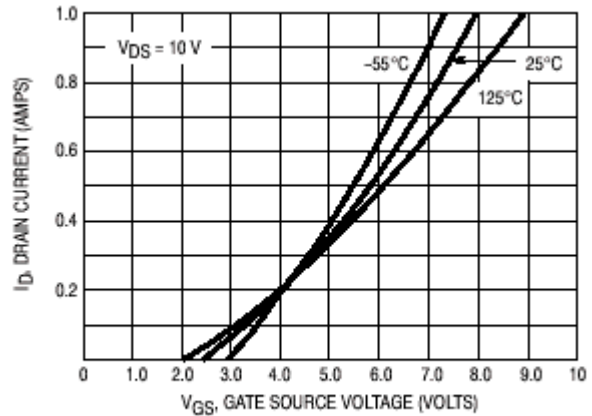


Figure 2. Transfer Characteristics

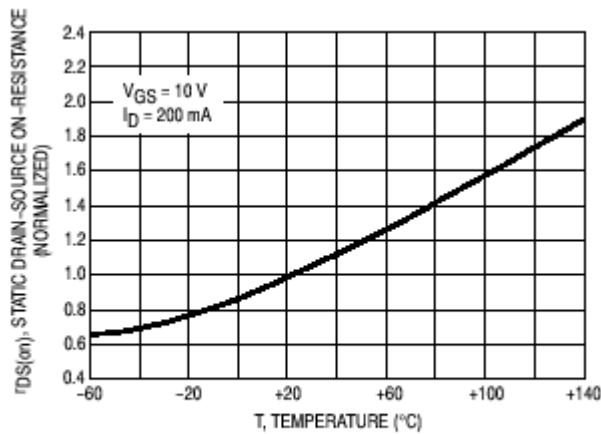


Figure 3. Temperature versus Static Drain-Source On-Resistance

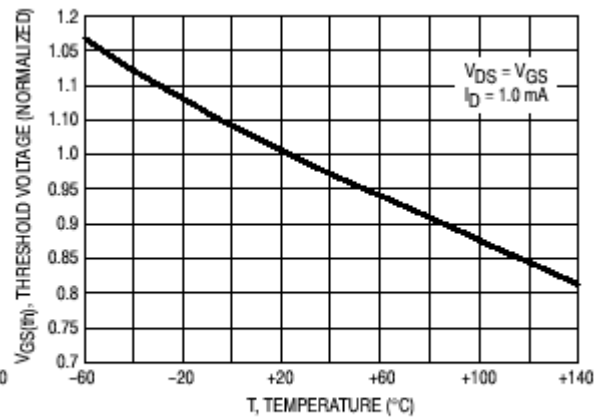


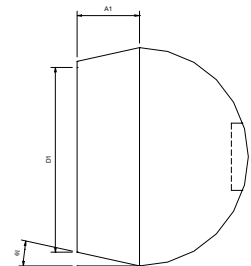
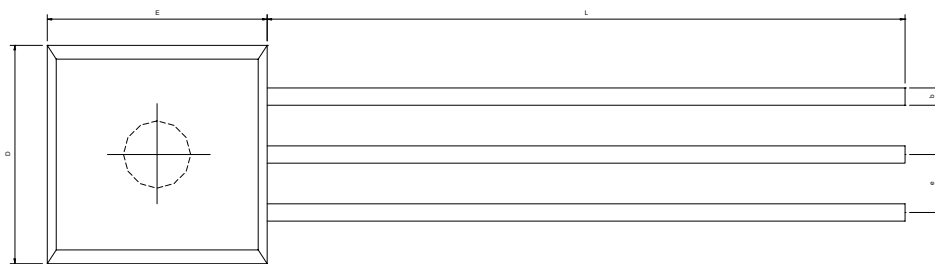
Figure 4. Temperature versus Gate Threshold Voltage

PACKAGE DIMENSION

TO-92



| SYMBOLS | DIMENSIONS IN MILLIMETERS | | | DIMENSIONS IN INCHES | | |
|---------|---------------------------|-------|-------|----------------------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 3.45 | 3.56 | 3.66 | 0.136 | 0.140 | 0.144 |
| A1 | 1.22 | 1.30 | 1.37 | 0.048 | 0.051 | 0.054 |
| b | --- | 0.38 | --- | --- | 0.015 | --- |
| D | 4.27 | 4.52 | 4.78 | 0.168 | 0.178 | 0.188 |
| D1 | 4.14 | 4.29 | 4.45 | 0.163 | 0.169 | 0.175 |
| E | 4.32 | 4.57 | 4.83 | 0.170 | 0.180 | 0.190 |
| L | 12.98 | 13.49 | 14.00 | 0.511 | 0.531 | 0.551 |
| e | --- | 1.27 | --- | --- | 0.050 | --- |
| θ | --- | 5° | --- | --- | 5° | --- |
| θ1 | --- | 5° | --- | --- | 5° | --- |



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